



Serial No. 09/893,455  
SKI.007D  
Amendment dated February 5, 2004

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re PATENT APPLICATION of

Hiroyuki Nishi et al.

Group Art Unit: 1732

Serial No.: 09/893,455

Examiner: A. Ortiz

Filed: June 29, 2001

Confirm. No.: 7179

For: **TRANSFER MOLDING METHOD FOR MANUFACTURING SEMICONDUCTOR  
DEVICES**

---

**AMENDMENT UNDER 37 C.F.R. 1.116**

U.S. Patent and Trademark Office  
2011 South Clark Place  
Customer Window, **Mail Stop AF**  
Crystal Plaza Two, Lobby, Room 1B03  
Arlington, VA 22202

Date: February 5, 2004

Sir:

In response to the Final Office Action dated November 6, 2003, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 7 of this paper.

*Handwritten:* OIP E JC87  
2/5/04